

INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Not for submission under 37 CFR 1.99)	Application Number		10595384
	Filing Date		2006-04-13
	First Named Inventor	Christopher Hess	
	Art Unit	2857	
	Examiner Name		
Attorney Docket Number		D5116-00051	

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	3	Buehler, M. G., "Microelectronic Test Chips for VLSI Electronics," VLSI Electronics Microstructure Science, pp. 529-576, Vol. 6, Chapter 9, Academic Press, 1983	<input type="checkbox"/>
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	5	Hess, C., Welland, L. H., "Influence of Short Circuits on Data of Contact & Via Open Circuits Determined by a Novel Weave Test Structure," IEEE Transactions on Semiconductor Manufacturing, pp. 27-34, Vol. 9, No. 1, 1996	<input type="checkbox"/>
	6	Hess, C., Stashower, D., Stine, B. E., Welland, L. H., Verma, G., Miyamoto, K., Inoue, K., "Fast Extraction of Defect Size Distribution Using a Single Layer Short Flow NEST Structure", IEEE Transactions on Semiconductor Manufacturing, pp. 330-337, Vol. 14, No. 4, 2001	<input type="checkbox"/>
	7	Walton, A. J., Ward, D., Robertson, J. M., Holwill R. J., "A Novel Approach for an Electrical Vernier to Measure Mask Misalignment", pp. 950-953, 19th European Solid State Device Research Conference ESSDERC '89, Springer Verlag, 1989	<input type="checkbox"/>
	8	Hess, C., Stine, B. E., Welland, L. H., Mitchell, T., Kamett, M., Gardner, K., "Passive Multiplexer Test Structure For Fast and Accurate Contact and Via Fail Rate Evaluation", pp. 163-167, Proc. International Conference on Microelectronic Test Structures (ICMTS), Vol. 15, Cork (Ireland), 2002	<input type="checkbox"/>
	9	Walton, A. J., Gammie, W., Marrow, D., Stevenson, J. T. M., Holwill, R. J., "A Novel Approach for Reducing the Area Occupied by Contact Pads on Process Control Chips", International Conference on Microelectronic Test Structures, San Diego, (USA), 1990	<input type="checkbox"/>
	10	Hess, C., Welland, L. H., Bornfeld, R., "Customized Checkerboard Test Structures to Localize Interconnection Point Defects", Proc. VLSI Multilevel Interconnection Conference (VMIC), pp. 163-168, Santa Clara (USA), 1997	<input type="checkbox"/>

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11	Hess, C., Weiland, L. H., "Defect Parameter Extration in Backend Process Steps using a Multilayer Checkerboard Test Structure", Proc. International Conference on Microelectronic Test Structures (ICMTS), pp. 51-56, Nara (Japan), 1995	<input type="checkbox"/>
12	Hess, C., Weiland, L. H., "Strategy to Disentangle Multiple Faults to Identify Random Defects within Test Structures", Proc. International Conference on Microelectronic Test Structures (ICMTS), pp. 141-146, Kanazawa (Japan), 1998	<input type="checkbox"/>
13	Hess, C., Weiland, L. H., "Harp Test Structure to Electrically Determine Size Distributions of Killer Defects", IEEE Transactions on Semiconductor Manufacturing, pp. 194-203, Vol. 11, No. 2, 1998	<input type="checkbox"/>
14	Hess, C., Weiland, L. H., "Drop in Process Control Checkerboard Test Structure for Efficient Online Process Characterization and Defect Problem Debugging", Proc. International Conference on Microelectronic Test Structures (ICMTS), pp. 152-159, San Diego (USA), 1994	<input type="checkbox"/>
15	Hess, C., Weiland, L. H., Lau, G., Simonet, P., "Control of Application Specific Interconnection on Gate Arrays Using an Active Checkerboard Test Structure", Proc. International Conference on Microelectronic Test Structures (ICMTS), pp. 55-60, Trento (Italy), 1996	<input type="checkbox"/>
16	Doong, K., Hsieh, S., Lin, S., Shen, B. Cheng, J., Hess, C., Weiland, L., Hsu, C., "Addressable Failure Site Test Structures (AFS-TS) for CMOS Processes: Design Guidelines, Fault Simulation, and Implementation", IEEE Transactions on Semiconductor Manufacturing, pp. 338-355, Vol. 14, No. 4, 2001	<input type="checkbox"/>
17	Ward, D., Walton, A. J., Gammie, W. G., Holwill, R. J., "The Use of a Digital Multiplexer to Reduce Process Control Chip Pad Count", International Conference on Microelectronic Test Structures, Vol. 5, San Diego (USA), 1992	<input type="checkbox"/>
18	Khare, J., Maly, W., Griep, S., Schmitt-Landsiedel, D., "SRAM-based Extraction of Defect Characteristics", International Conference on Microelectronic Test Structures, Vol. 7, San Diego, USA, 1994	<input type="checkbox"/>

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- ☐ See attached certification statement.
- ☐ Fee set forth in 37 CFR 1.17 (p) has been submitted herewith.
- ☒ None

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A signature of the applicant or representative is required in accordance with CFR 1.33, 10.18. Please see CFR 1.4(d) for the form of the signature.

Signature	/Richard A. Paikoff/	Date (YYYY-MM-DD)	2007-08-15
Name/Print	Richard A. Paikoff	Registration Number	34,892

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